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**PATENT** 

Submission Type	Conveyance Type		
K) New	(X) Assignment ( ) Security Agreement		
) Resubmission (Non-Recordation) Document ID#	( ) License ( ) Change of Name ( ) Merger ( ) Other		
Correction of PTO Error Reel # Frame #	U.S. Government (For Use ONLY by U.S. Government Agencies		
( ) Corrective Document Reel # Frame #	( ) Departmental File ( ) Secret Fil		
Conveying Parties	Execution date		
Masao YAMADA	April 24, 2001		
Shinichi KONDA	April 25, 2001		
Similar Rolling	•		
Taketoshi SATO	April 25, 2001		
Taketoshi SATO  09/85270	April 25, 2001		
Taketoshi SATO  9/85270  Receiving Party ()Mark if	April 25, 2001		
Taketoshi SATO  9/85270  Receiving Party ()Mark if  DENSO CORPORATION	April 25, 2001		
Taketoshi SATO  9/85270  Receiving Party ()Mark if  DENSO CORPORATION  1-1, Showa-cho	April 25, 2001		
Taketoshi SATO 09/85270	April 25, 2001		

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> **PATENT REEL: 011799 FRAME: 0970**

PATENT REEL: 011799 FRAME: 0971

## **ASSIGNMENT**

For good and valuable consideration, the receipt of which is hereby expressly acknowledged, the undersigned hereby agree(s) to assign, and hereby sell(s), assign(s) and transfer(s) to

DENSO CORPORATION: 1-1, Showa-cho, Kariya-city, Aichi-pref., 448-8661, Japan

as Assignee, and its successors, assigns and legal representatives, the entire right, title and interest, in the United States of America and all foreign countries, to certain inventions known as

SEMICONDUCTOR DEVICE MOUNT STRUCTURE HAVING HEAT DISSIPATING
MEMBER FOR DISSIPATING HEAT GENERATED FROM SEMICONDUCTOR DEVICE

described in an application for Letters Patent of the United States executed

(C) As U.S. Application Serial No. Filed on

(A) X On even date herewith

RECORDED: 05/11/2001

(B) On

as well as any and all continuations, d Letters Patent, and all Letters Patent authorize(s) and request(s) the United S Letters Patent to said Assignee.	that may be granted therefor	or. The undersigned hereby
The undersigned agree(s), when reques acts which may be necessary for securinuitle thereto in said Assignee.	sted, to sign all papers, take all ng and maintaining patents for	rightful oaths, and perform all said inventions and for vesting
The undersigned authorize(s) and emporight of priority provided by the Internation any convention which may be henceforthesaid application for said Letters Patent.  The undersigned also authorize(s) La	onal Convention for the Protection substituted therefor, as may be away of the Office of David G. Posz	on of Industrial Property, or by e necessary in connection with to insert hereon any further
identification that may be necessary or de	estrable for recordation of this de	ocument.
Masac Yumada	(4) Date	Makete Sto Witness
Inventor 1: Masao YAMADA	Date	Witness
Simila Konda	Apr:/25.2001	Makoto Sto
Inventor 2: Shinichi KONDA		Witness
Jaketoshi Sato	April 25,200/	Makoto Lto Witness  Makoto Lto
Inventor 3: Taketoshi SATO	Date	Witness
Inventor 4:	Date	Witness
Inventor 5:	Date	Witness
Continued on page 2 for additional inventors		

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